

APPARATUS FOR POLISHING AND METHOD FOR POLISHING

ABSTRACT

There is provided an apparatus for polishing an object to be polished using a polishing pad having a polishing surface, the apparatus including a polishing table for supporting the polishing pad, the polishing table being configured to be rotatable, a substrate holding unit configured to hold the object to be polished and pressing the object to be polished against the polishing pad, and a polishing-liquid removing unit configured to remove polishing liquid from the polishing surface. The polishing-liquid removing unit includes a rinse unit configured to jet cleaning liquid onto the polishing surface and a sucking unit configured to suck the polishing liquid on the polishing surface onto which the cleaning liquid is jetted. The rinse unit includes a cleaning space surrounded by a sidewall. The sidewall includes an opening section for opening the cleaning space toward a radial direction outer side of the polishing table.

Representative Drawing: Fig.31